



## V<sub>WM</sub> = 5V, 2pF ESD Protection Diode

#### **FEATURES**

- Meet IEC61000-4-2(ESD) ±15kV(air) , ±8kV(contact)
- Working Voltage: 5V
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### APPLICATIONS

- High Speed Data Lines: USB 2.0 / VGA/ DVI /SDI
- Notebooks, Desktops and Servers
- Touch Panel

### **MECHANICAL DATA**

- Case: DFN1006L
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: As marked
- Weight: 0.742mg (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
P <sub>PPSM</sub>	100	W	
I <sub>PP</sub>	3	А	
V <sub>WM</sub>	5	V	
$V_{BR}$ at $I_R = 1 \text{ mA}$	6	V	
$V_{C}$ at $I_{PP}$ = 3 A	15	V	
Package	DFN1006L		
Configuration	Single die		











# TESD5V0L1UC Taiwan Semiconductor

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	ТҮР	MAX	UNIT
Reverse breakdown voltage <sup>(1)</sup>	I <sub>R</sub> =1 mA	V <sub>BR</sub>	6	-	9.8	V
Rated working standoff voltage		V <sub>WM</sub>	-	-	5	V
Reverse current <sup>(1)</sup>	V <sub>R</sub> = 5 V	I <sub>R</sub>	-	-	0.1	μA
Clamping voltage <sup>(2)</sup>	I <sub>PP</sub> = 1 A	N	-	-	10	V
Clamping voltage <sup>(2)</sup>	I <sub>PP</sub> = 3 A	V <sub>C</sub>	-	-	15	V
Junction capacitance	$f = 1MHz, V_R = 0V$	CJ	-	-	2	pF

#### Notes:

- 1. Pulse test with PW = 30ms
- 2.  $tp = 8/20\mu s$  waveform

ORDERING INFORMATION			
ORDERING CODE	PACKAGE	PACKING	
TESD5V0L1UC RJG	DFN1006L	10K / 7" Reel	



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 



Fig.2 ESD pulse waveform according to IEC 61000-4-2 110 100 90 **PEAK IMPULSE CURRENT(%)** 80 70 60 50 40 30 20 10 0 -10 10 30 50 70 t(ns) t<sub>r</sub>=0.7ns to 1ns

Fig.3 TLP I-V Curve

-0.2

-0.8

-1.4

-2.0

-2.6

-3.2

-18

-16

-14

-12

-10

-8

TLP VOLTAGE(V)

-6

TLP CURRENT(A)





-2

-4



## PACKAGE OUTLINE DIMENSION









DIM.	Unit (mm		Unit (inch)	
	Min.	Max.	Min.	Max.
A	0.46	0.51	0.018	0.020
b	0.50 (TYP.)		0.020 (TYP.)	
D	0.95	1.05	0.037	0.041
E	0.55	0.65	0.022	0.026
L	0.30	(TYP.)	0.012	(TYP.)

## SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	0.56	0.022
В	0.41	0.016
С	1.11	0.044



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